

## HIGH VOLTAGE ULTRAFAST RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

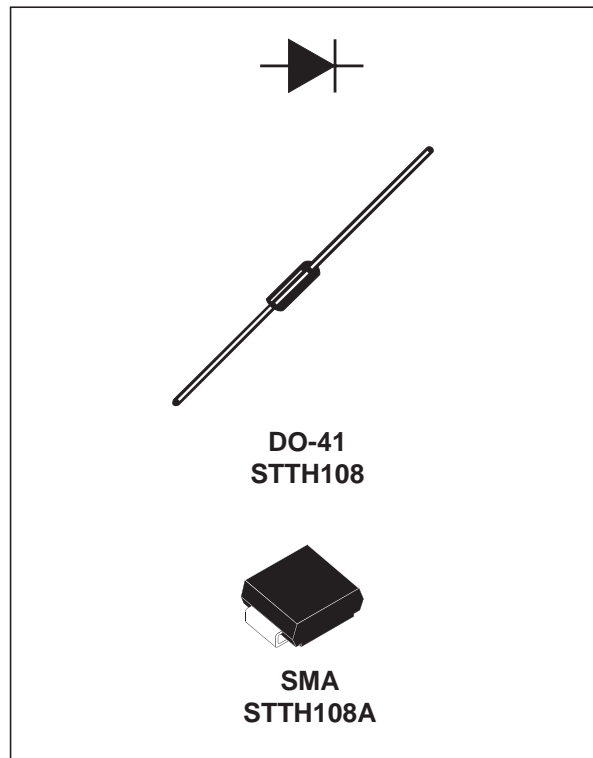
<b>I<sub>F(AV)</sub></b>	<b>1 A</b>
<b>V<sub>RRM</sub></b>	<b>800 V</b>
<b>T<sub>j</sub> (max)</b>	<b>175 °C</b>
<b>V<sub>F</sub> (max)</b>	<b>1.25 V</b>

### FEATURES AND BENEFITS

- Low forward voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology

### DESCRIPTION

The STTH108, which is using ST ultrafast high voltage planar technology, is specially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage			800	V
V <sub>(RMS)</sub>	RMS voltage			560	V
I <sub>F(AV)</sub>	Average forward current	TI = 110°C δ = 0.5	DO-41	1	A
		TI = 130°C δ = 0.5	SMA	1	
I <sub>FSM</sub>	Forward surge current t = 8.3 ms	DO-41		25	A
		SMA		20	
T <sub>stg</sub>	Storage temperature range			- 50 + 175	°C
T <sub>j</sub>	Maximum operating junction temperature			+ 175	°C

## THERMAL PARAMETERS

Symbol	Parameter			Value	Unit
$R_{th(j-l)}$	Junction to lead	L = 10 mm	DO-41	45	°C/W
			SMA	30	
$R_{th(j-a)}$	Junction to ambient	L = 10 mm	DO-41	110	

## STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R$	Reverse leakage current	$V_R = 800V$	$T_j = 25^\circ C$			5	$\mu A$
			$T_j = 125^\circ C$			50	
$V_F$	Forward voltage drop	$I_F = 1 A$	$T_j = 25^\circ C$			1.65	V
			$T_j = 150^\circ C$		0.89	1.25	

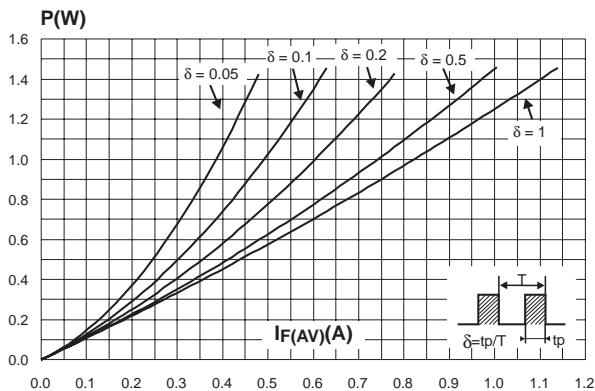
To evaluate the maximum conduction losses use the following equation :

$$P = 1.05 \times I_{F(AV)} + 0.20 I_{F(RMS)}^2$$

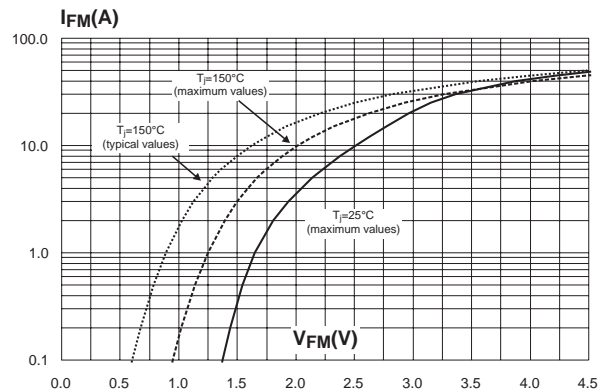
## DYNAMIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5 A$ $I_{rr} = 0.25 A$ $I_R = 1A$	$T_j = 25^\circ C$			75	ns
$t_{fr}$	Forward recovery time	$I_F = 1 A$ $dI_F/dt = 50 A/\mu s$ $V_{FR} = 1.1 \times V_{Fmax}$	$T_j = 25^\circ C$			200	ns
$V_{FP}$	Forward recovery voltage						12

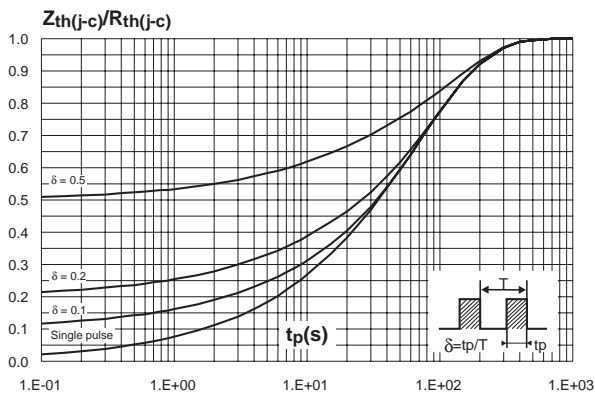
**Fig. 1:** Conduction losses versus average current.



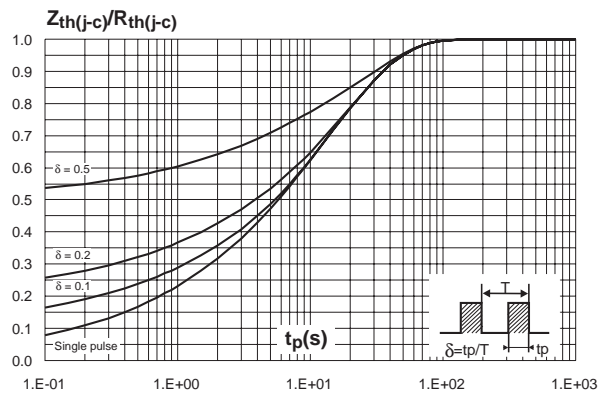
**Fig. 2:** Forward voltage drop versus forward current.



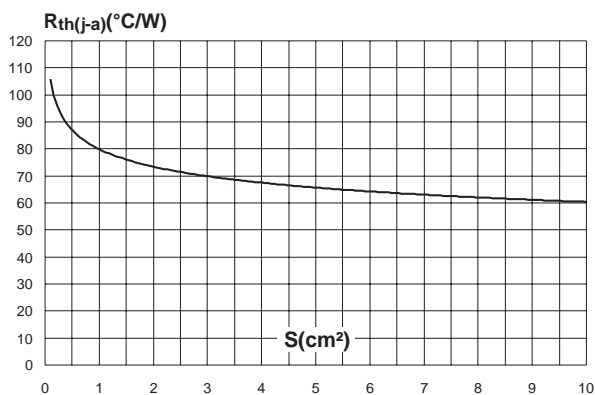
**Fig. 3-1:** Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4, L<sub>leads</sub> = 10mm) (DO-41).



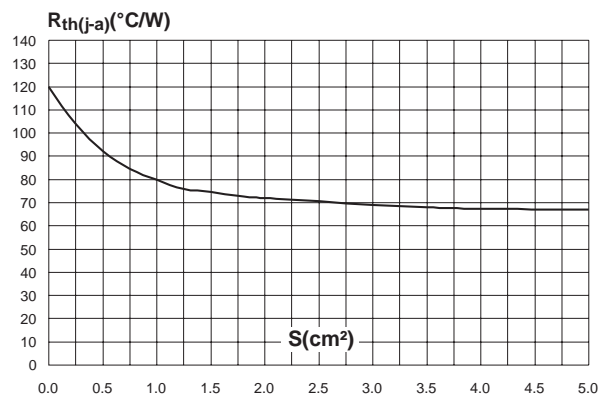
**Fig. 3-2:** Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4) (SMA).



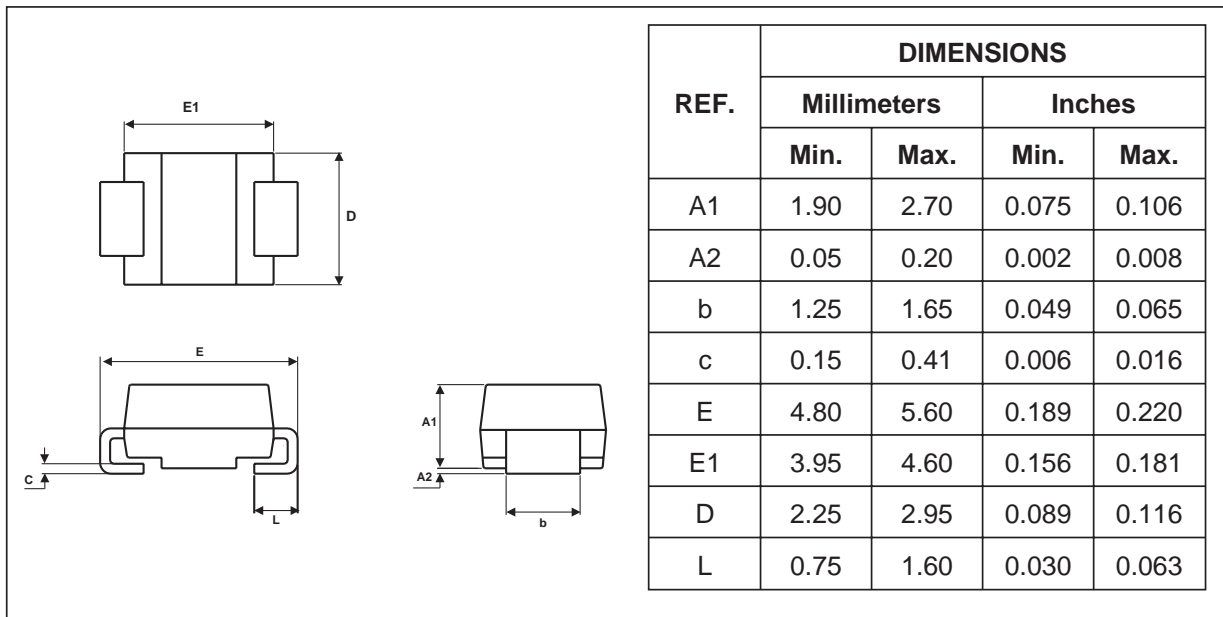
**Fig. 4-1:** Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed circuit board FR4, copper thickness: 35µm) (DO-41).



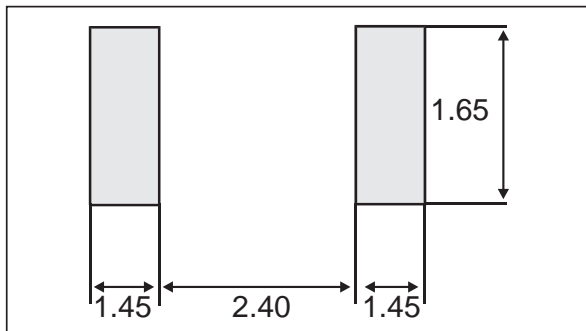
**Fig. 4-2:** Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed circuit board FR4, copper thickness: 35µm) (SMA).



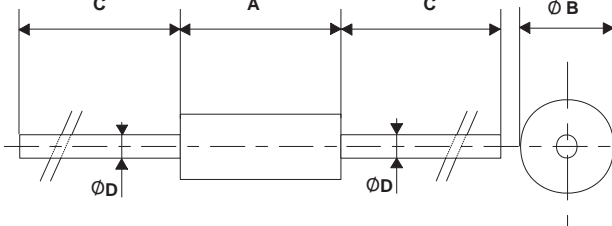
**PACKAGE MECHANICAL DATA**  
SMA



**FOOTPRINT (in millimeters)**



**PACKAGE MECHANICAL DATA**  
**DO41**

	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
	A	4.07	5.20	0.160
B	2.04	2.71	0.080	0.107
C	28		1.102	
D	0.712	0.863	0.028	0.034

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
STTH108	STTH108	DO-41	0.34 g	2000	Ammopack
STTH108A	H08	SMA	0.068 g	5000	Tape & reel
STTH108RL	STTH108	DO-41	0.34 g	5000	Tape & reel

- Epoxy meets UL 94,V0

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